

SOT1799-5

CFM6F, ceramic flange mount flat package; 6 terminals; 5.36 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

10 July 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	CFM6F
Package style descriptive code	CFMF (ceramic flange mount flat)
Package body material type	C (ceramic)
Mounting method type	S (surface mount)
Issue date	30-05-2018
Manufacturer package code	98ASA01118D

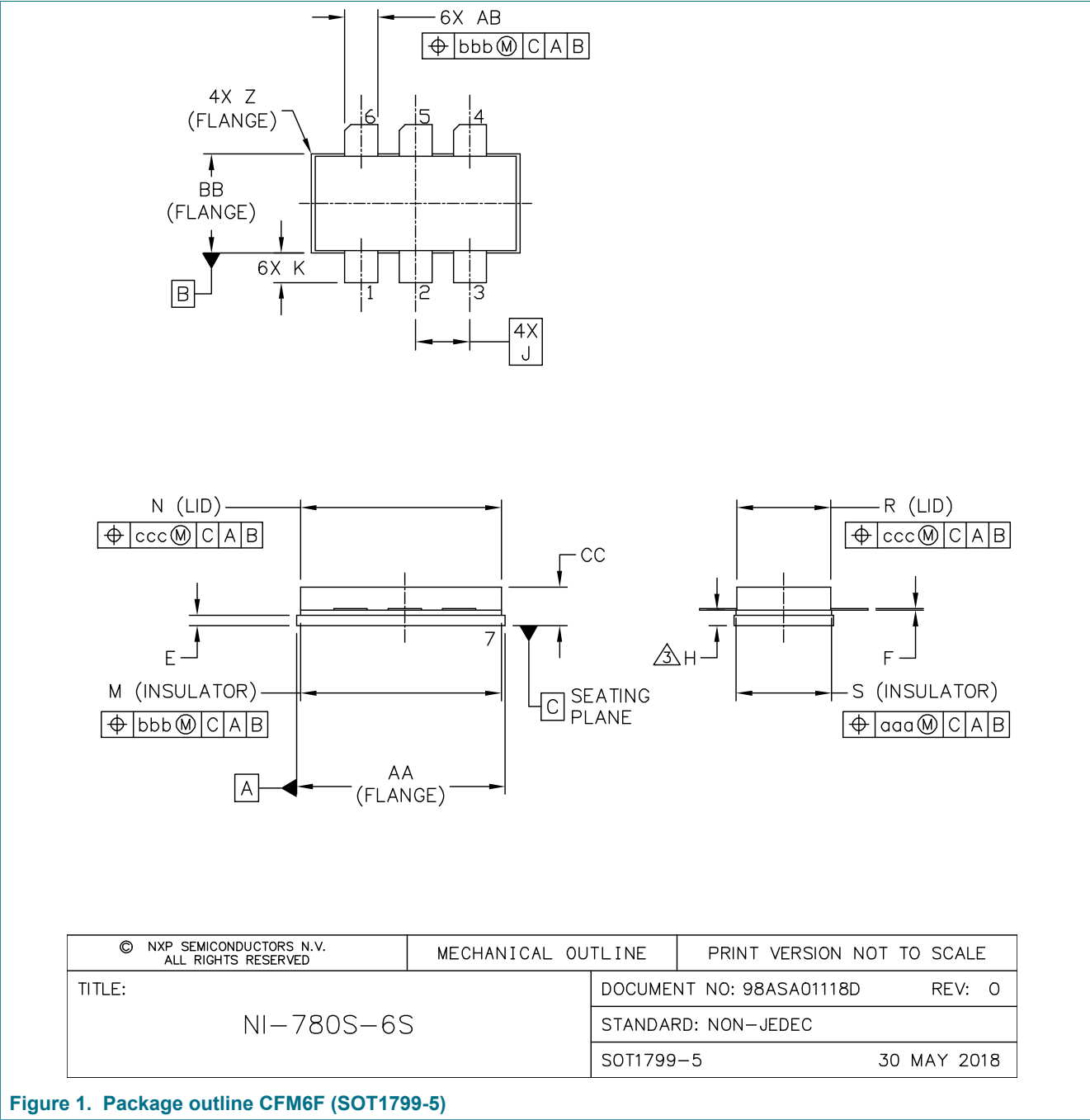
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.7	9.78	9.86	mm
package width	20.45	20.58	20.7	mm
package height	3.18	3.75	4.32	mm
nominal pitch	-	5.36	-	mm
actual quantity of termination	-	6	-	



CFM6F, ceramic flange mount flat package; 6 terminals; 5.36 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

2 Package outline



CFM6F, ceramic flange mount flat package; 6 terminals; 5.36 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
- 2. CONTROLLING DIMENSION: INCH.

3. DIMENSION H IS MEASURED .030 INCH (0.762 MM) AWAY FROM FLANGE PARALLEL TO DATUM B TO CLEAR EPOXY FLOW OUT.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	Z	R. 000	R.040	R0. 00	R1.02
BB	.382	.388	9.70	9.86	AB	. 124	. 134	3. 15	3. 40
CC	.125	.170	3.18	4.32	aaa	.005		0.13	
E	.035	.045	0.89	1.14	bbb	.010		0.25	
F	.003	.006	0.08	0.15	ccc	.015		0.38	
H	.057	.067	1.45	1.70					
J	. 211 BSC		5. 36 BSC						
K	.0995	.1295	2.53	3.29					
M	.774	.786	19.66	19.96					
N	.772	.788	19.61	20.02					
R	.365	.375	9.27	9.53					
S	.365	.375	9.27	9.53					
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TITLE: NI-780S-6S					DOCUMENT NO: 98ASA01118D REV: 0				
					STANDARD: NON-JEDEC				
					SOT1799-5				

Figure 2. Package outline note CFM6F (SOT1799-5)

3 Legal information

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